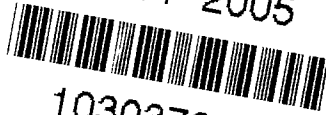


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Wei Wang
Soo Jin Chua

Additional name(s) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies):

Institute of Materials Research and
Engineering
3 Research Link
Singapore 117602

Additional names/addresses attached? ☐ Yes ☒ No

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ASSIGNMENT

For valuable consideration, we, WEI WANG of #03-03 dunearn Lodge, 408 Duneran Road, Singapore 289674, and SOO JIN CHUA of 37 Cheng Soon Crescent, Singapore 599909, hereby assign to:

Institute of Materials Research and Engineering, a Singapore corporation having a place of business at:

3 Research Link
Singapore 117602; and

its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us, entitled LAMINATES FOR ENCAPSULATING DEVICES, filed March 9, 2001, and assigned U.S. Serial Number 09/786,833, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.



WEI WANG

24/01/02

Date

SOO JIN CHUA
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Date

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WEI WANG

Date



SOO JIN CHUA
50067934.doc

Date

